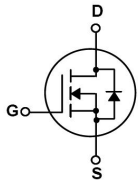
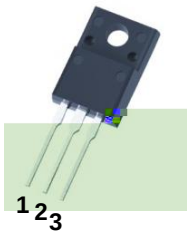


/ Descriptions**/ Features**

/ /

/ Applications

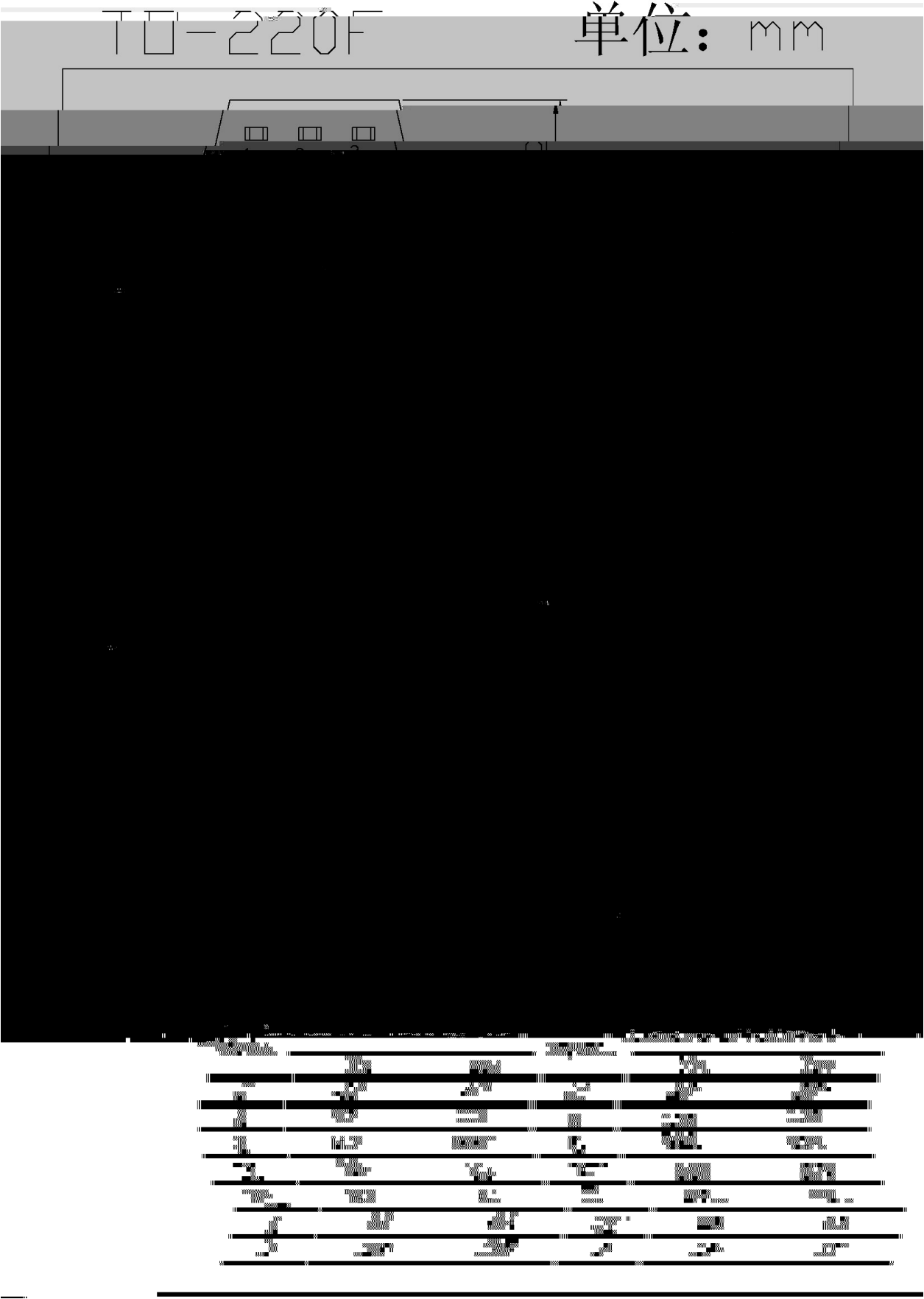
GF2GF

/ Equivalent Circuit**/ Pinning****/ h_{FE} Classifications & Marking**

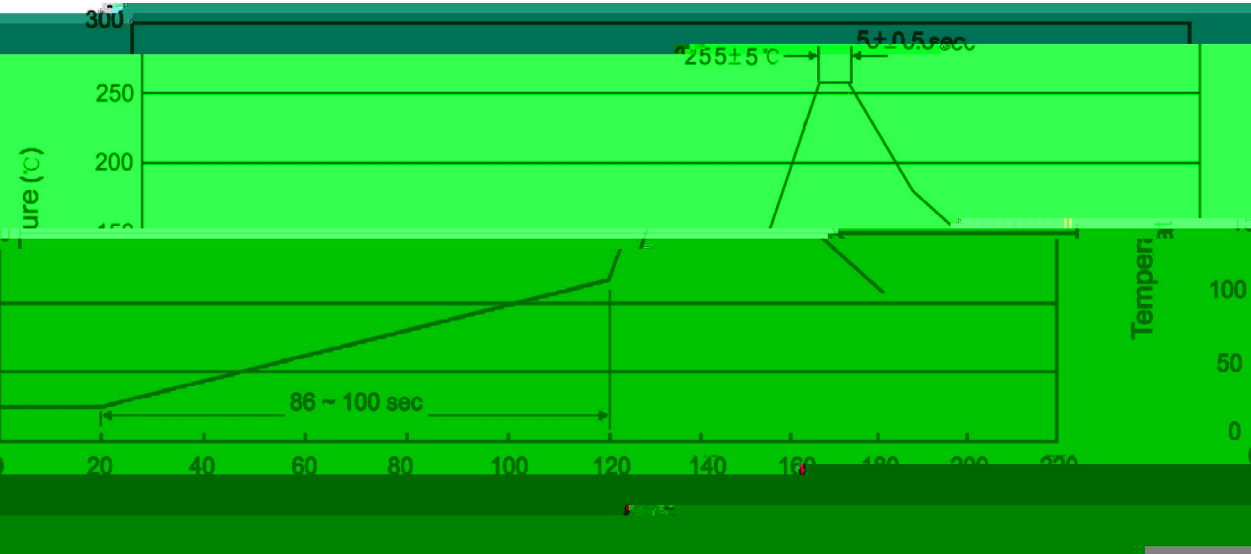
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/ Electrical Characteristic Curve

/ Package Dimensions



() / Temperature Profile for Dip Soldering(Pb-Free)



$\frac{3}{8}$

2

$\frac{3}{8}$

2

$\frac{3}{8}$

2

$\frac{3}{8}$

2

/ Resistance to Soldering Heat Test Conditions

2

$\frac{3}{8}$

2

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

封装形式	包装数量					包装尺寸		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices